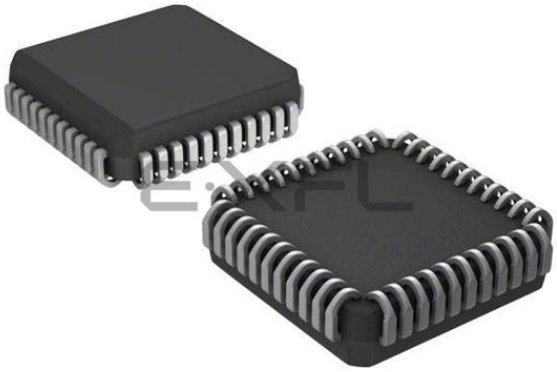

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Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f874-04i-l

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TABLE 1-2: PIC16F874 AND PIC16F877 PINOUT DESCRIPTION

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	13	14	30	I	ST/CMOS(4)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	14	15	31	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	1	2	18	I/P	ST	Master Clear (Reset) input or programming voltage input. This pin is an active low RESET to the device.
						PORTA is a bi-directional I/O port.
RA0/AN0	2	3	19	I/O	TTL	RA0 can also be analog input0.
RA1/AN1	3	4	20	I/O	TTL	RA1 can also be analog input1.
RA2/AN2/VREF-	4	5	21	I/O	TTL	RA2 can also be analog input2 or negative analog reference voltage.
RA3/AN3/VREF+	5	6	22	I/O	TTL	RA3 can also be analog input3 or positive analog reference voltage.
RA4/T0CKI	6	7	23	I/O	ST	RA4 can also be the clock input to the Timer0 timer/ counter. Output is open drain type.
RA5/$\overline{SS}$/AN4	7	8	24	I/O	TTL	RA5 can also be analog input4 or the slave select for the synchronous serial port.
						PORTB is a bi-directional I/O port. PORTB can be soft-ware programmed for internal weak pull-up on all inputs.
RB0/INT	33	36	8	I/O	TTL/ST(1)	RB0 can also be the external interrupt pin.
RB1	34	37	9	I/O	TTL	
RB2	35	38	10	I/O	TTL	
RB3/PGM	36	39	11	I/O	TTL	RB3 can also be the low voltage programming input.
RB4	37	41	14	I/O	TTL	Interrupt-on-change pin.
RB5	38	42	15	I/O	TTL	Interrupt-on-change pin.
RB6/PGC	39	43	16	I/O	TTL/ST(2)	Interrupt-on-change pin or In-Circuit Debugger pin. Serial programming clock.
RB7/PGD	40	44	17	I/O	TTL/ST(2)	Interrupt-on-change pin or In-Circuit Debugger pin. Serial programming data.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as an external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).
4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

NOTES:

2.2.2.2 OPTION_REG Register

The OPTION_REG Register is a readable and writable register, which contains various control bits to configure the TMR0 prescaler/WDT postscaler (single assignable register known also as the prescaler), the External INT Interrupt, TMR0 and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer.

REGISTER 2-2: OPTION_REG REGISTER (ADDRESS 81h, 181h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

bit 7 **$\overline{\text{RBPU}}$:** PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6 **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5 **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4 **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3 **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

Note: When using low voltage ICSP programming (LVP) and the pull-ups on PORTB are enabled, bit 3 in the TRISB register must be cleared to disable the pull-up on RB3 and ensure the proper operation of the device

2.2.2.8 PCON Register

The Power Control (PCON) Register contains flag bits to allow differentiation between a Power-on Reset (POR), a Brown-out Reset (BOR), a Watchdog Reset (WDT), and an external MCLR Reset.

Note:	BOR is unknown on POR. It must be set by the user and checked on subsequent RESETS to see if BOR is clear, indicating a brown-out has occurred. The BOR status bit is a “don’t care” and is not predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the configuration word).

REGISTER 2-8: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-1
—	—	—	—	—	—	POR	BOR
bit 7							bit 0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **POR**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **BOR**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

4.4 Reading the FLASH Program Memory

Reading FLASH program memory is much like that of EEPROM data memory, only two NOP instructions must be inserted after the RD bit is set. These two instruction cycles that the NOP instructions execute, will be used by the microcontroller to read the data out of program memory and insert the value into the EEDATH:EEDATA registers. Data will be available following the second NOP instruction. EEDATH and EEDATA will hold their value until another read operation is initiated, or until they are written by firmware.

The steps to reading the FLASH program memory are:

1. Write the address to EEADRH:EEADR. Make sure that the address is not larger than the memory size of the PIC16F87X device.
2. Set the EEPGD bit to point to FLASH program memory.
3. Set the RD bit to start the read operation.
4. Execute two NOP instructions to allow the microcontroller to read out of program memory.
5. Read the data from the EEDATH:EEDATA registers.

EXAMPLE 4-3: FLASH PROGRAM READ

```
BSF     STATUS, RP1    ;
BCF     STATUS, RP0    ;Bank 2
MOVF    ADDRL, W       ;Write the
MOVWF   EEADR          ;address bytes
MOVF    ADDRH,W        ;for the desired
MOVWF   EEADRH         ;address to read
BSF     STATUS, RP0    ;Bank 3
BSF     EECON1, EEPGD  ;Point to Program memory
BSF     EECON1, RD     ;Start read operation
NOP                    ;Required two NOPs
NOP                    ;
BCF     STATUS, RP0    ;Bank 2
MOVF    EEDATA, W      ;DATAL = EEDATA
MOVWF   DATAL          ;
MOVF    EEDATH,W       ;DATAH = EEDATH
MOVWF   DATAH          ;
```

4.5 Writing to the FLASH Program Memory

Writing to FLASH program memory is unique, in that the microcontroller does not execute instructions while programming is taking place. The oscillator continues to run and all peripherals continue to operate and queue interrupts, if enabled. Once the write operation completes (specification D133), the processor begins executing code from where it left off. The other important difference when writing to FLASH program memory, is that the WRT configuration bit, when clear, prevents any writes to program memory (see Table 4-1).

Just like EEPROM data memory, there are many steps in writing to the FLASH program memory. Both address and data values must be written to the SFRs. The EEPGD bit must be set, and the WREN bit must be set to enable writes. The WREN bit should be kept clear at all times, except when writing to the FLASH Program memory. The WR bit can only be set if the WREN bit was set in a previous operation, i.e., they both cannot be set in the same operation. The WREN bit should then be cleared by firmware after the write. Clearing the WREN bit before the write actually completes will not terminate the write in progress.

Writes to program memory must also be prefaced with a special sequence of instructions that prevent inadvertent write operations. This is a sequence of five instructions that must be executed without interruption for each byte written. These instructions must then be followed by two NOP instructions to allow the microcontroller to setup for the write operation. Once the write is complete, the execution of instructions starts with the instruction after the second NOP.

The steps to write to program memory are:

1. Write the address to EEADRH:EEADR. Make sure that the address is not larger than the memory size of the PIC16F87X device.
2. Write the 14-bit data value to be programmed in the EEDATH:EEDATA registers.
3. Set the EEPGD bit to point to FLASH program memory.
4. Set the WREN bit to enable program operations.
5. Disable interrupts (if enabled).
6. Execute the special five instruction sequence:
   - Write 55h to EECON2 in two steps (first to W, then to EECON2)
   - Write AAh to EECON2 in two steps (first to W, then to EECON2)
   - Set the WR bit
7. Execute two NOP instructions to allow the microcontroller to setup for write operation.
8. Enable interrupts (if using interrupts).
9. Clear the WREN bit to disable program operations.

6.1 Timer1 Operation in Timer Mode

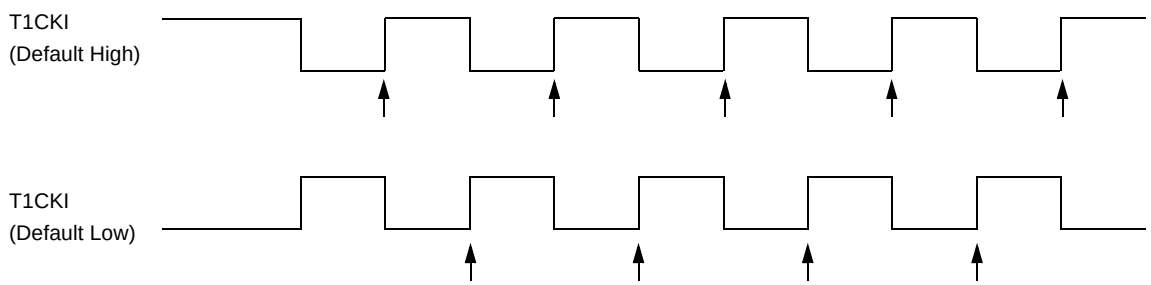
Timer mode is selected by clearing the TMR1CS (T1CON<1>) bit. In this mode, the input clock to the timer is FOSC/4. The synchronize control bit $\overline{\text{T1SYNC}}$ (T1CON<2>) has no effect, since the internal clock is always in sync.

6.2 Timer1 Counter Operation

Timer1 may operate in either a Synchronous, or an Asynchronous mode, depending on the setting of the TMR1CS bit.

When Timer1 is being incremented via an external source, increments occur on a rising edge. After Timer1 is enabled in Counter mode, the module must first have a falling edge before the counter begins to increment.

FIGURE 6-1: TIMER1 INCREMENTING EDGE



Note: Arrows indicate counter increments.

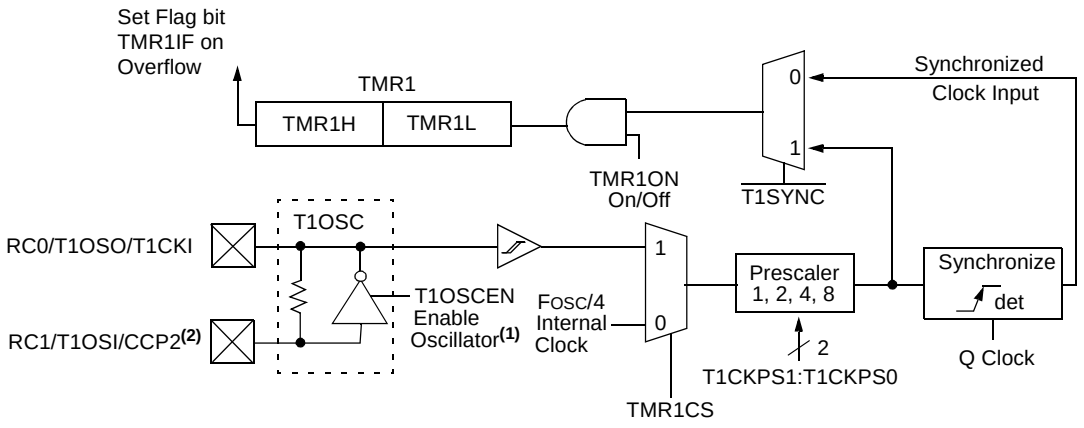
6.3 Timer1 Operation in Synchronized Counter Mode

Counter mode is selected by setting bit TMR1CS. In this mode, the timer increments on every rising edge of clock input on pin RC1/T1OSI/CCP2, when bit T1OSCEN is set, or on pin RC0/T1OSO/T1CKI, when bit T1OSCEN is cleared.

If $\overline{\text{T1SYNC}}$ is cleared, then the external clock input is synchronized with internal phase clocks. The synchronization is done after the prescaler stage. The prescaler stage is an asynchronous ripple-counter.

In this configuration, during SLEEP mode, Timer1 will not increment even if the external clock is present, since the synchronization circuit is shut-off. The prescaler, however, will continue to increment.

FIGURE 6-2: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter is turned off. This eliminates power drain.

6.7 Resetting of Timer1 Register Pair (TMR1H, TMR1L)

TMR1H and TMR1L registers are not reset to 00h on a POR, or any other RESET, except by the CCP1 and CCP2 special event triggers.

T1CON register is reset to 00h on a Power-on Reset, or a Brown-out Reset, which shuts off the timer and leaves a 1:1 prescale. In all other RESETS, the register is unaffected.

6.8 Timer1 Prescaler

The prescaler counter is cleared on writes to the TMR1H or TMR1L registers.

TABLE 6-2: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh,8Bh, 10Bh, 18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR1ON	--00 0000	--uu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.
Note 1: Bits PSPIE and PSPIF are reserved on the PIC16F873/876; always maintain these bits clear.

REGISTER 8-1: CCP1CON REGISTER/CCP2CON REGISTER (ADDRESS: 17h/1Dh)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CCPxX	CCPxY	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit 7							bit 0

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **CCPxX:CCPxY**: PWM Least Significant bits

Capture mode:
Unused

Compare mode:
Unused

PWM mode:
These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.

bit 3-0 **CCPxM3:CCPxM0**: CCPx Mode Select bits

0000 = Capture/Compare/PWM disabled (resets CCPx module)
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode, set output on match (CCPxIF bit is set)
1001 = Compare mode, clear output on match (CCPxIF bit is set)
1010 = Compare mode, generate software interrupt on match (CCPxIF bit is set, CCPx pin is unaffected)
1011 = Compare mode, trigger special event (CCPxIF bit is set, CCPx pin is unaffected); CCP1 resets TMR1; CCP2 resets TMR1 and starts an A/D conversion (if A/D module is enabled)
11xx = PWM mode

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

TABLE 9-2: DATA TRANSFER RECEIVED BYTE ACTIONS

Status Bits as Data Transfer is Received		SSPSR → SSPBUF	Generate $\overline{ACK}$ Pulse	Set bit SSPIF (SSP Interrupt occurs if enabled)
BF	SSPOV			
0	0	Yes	Yes	Yes
1	0	No	No	Yes
1	1	No	No	Yes
0	1	Yes	No	Yes

Note: Shaded cells show the conditions where the user software did not properly clear the overflow condition.

9.2.1.3 Slave Transmission

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit, and the SCL pin is held low. The transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then, the SCL pin should be enabled by setting bit CKP (SSPCON<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 9-7).

An SSP interrupt is generated for each data transfer byte. The SSPIF flag bit must be cleared in software and the SSPSTAT register is used to determine the status of the byte transfer. The SSPIF flag bit is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the $\overline{ACK}$ pulse from the master receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line is high (not $\overline{ACK}$), then the data transfer is complete. When the not $\overline{ACK}$ is latched by the slave, the slave logic is reset and the slave then monitors for another occurrence of the START bit. If the SDA line was low ($\overline{ACK}$), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then the SCL pin should be enabled by setting the CKP bit.

FIGURE 9-6: I²C WAVEFORMS FOR RECEPTION (7-BIT ADDRESS)

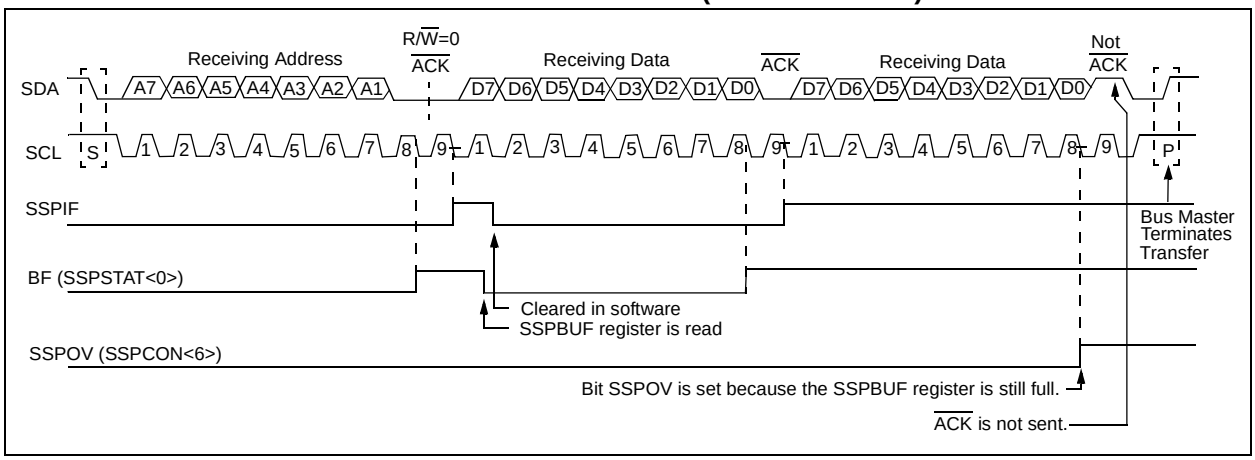
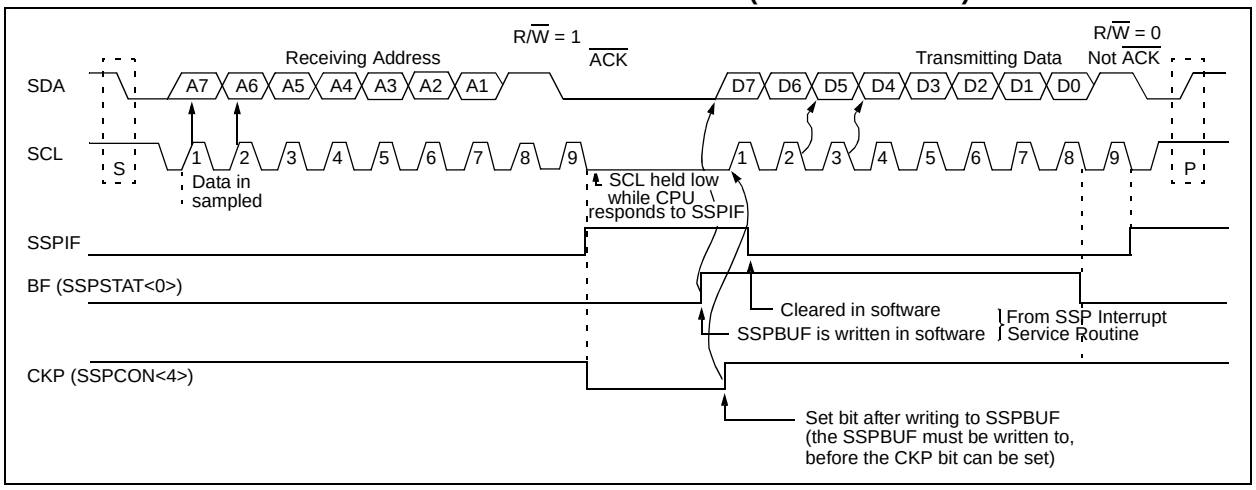


FIGURE 9-7: I²C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)



9.2.2 GENERAL CALL ADDRESS SUPPORT

The addressing procedure for the I²C bus is such that the first byte after the START condition usually determines which device will be the slave addressed by the master. The exception is the general call address, which can address all devices. When this address is used, all devices should, in theory, respond with an acknowledge.

The general call address is one of eight addresses reserved for specific purposes by the I²C protocol. It consists of all 0's with R/$\overline{W}$ = 0.

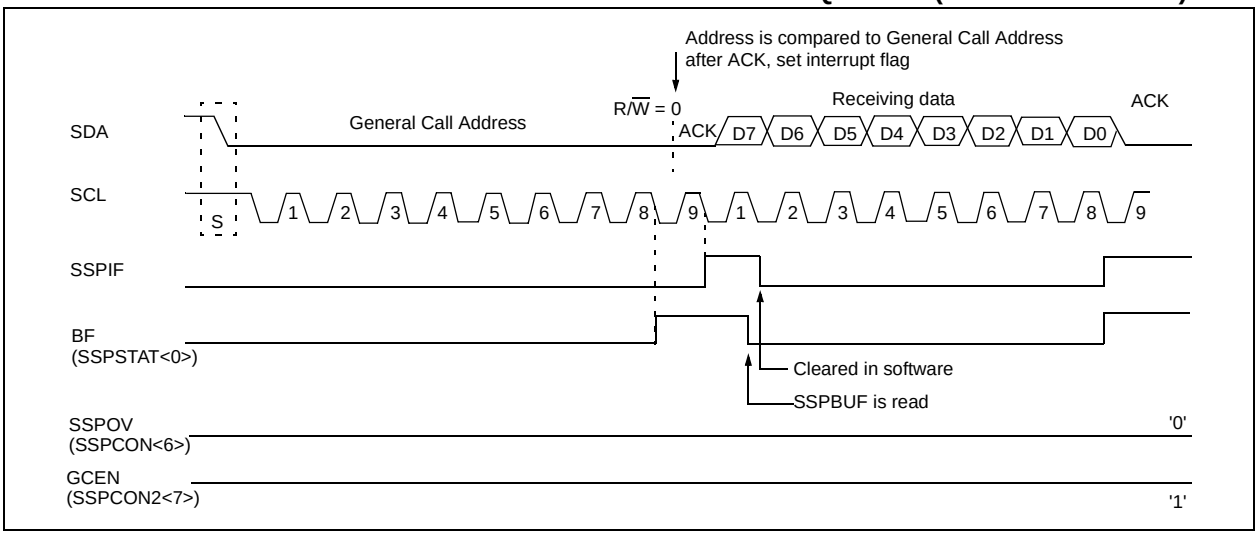
The general call address is recognized when the General Call Enable bit (GCEN) is enabled (SSPCON2<7> is set). Following a START bit detect, 8 bits are shifted into SSPSR and the address is compared against SSPADD. It is also compared to the general call address and fixed in hardware.

If the general call address matches, the SSPSR is transferred to the SSPBUF, the BF flag is set (eighth bit), and on the falling edge of the ninth bit ($\overline{ACK}$ bit), the SSPIF flag is set.

When the interrupt is serviced, the source for the interrupt can be checked by reading the contents of the SSPBUF to determine if the address was device specific, or a general call address.

In 10-bit mode, the SSPADD is required to be updated for the second half of the address to match, and the UA bit is set (SSPSTAT<1>). If the general call address is sampled when GCEN is set, while the slave is configured in 10-bit address mode, then the second half of the address is not necessary, the UA bit will not be set, and the slave will begin receiving data after the Acknowledge (Figure 9-8).

FIGURE 9-8: SLAVE MODE GENERAL CALL ADDRESS SEQUENCE (7 OR 10-BIT MODE)



9.2.10 I²C MASTER MODE REPEATED START CONDITION TIMING

A Repeated START condition occurs when the RSEN bit (SSPCON2<1>) is programmed high and the I²C module is in the IDLE state. When the RSEN bit is set, the SCL pin is asserted low. When the SCL pin is sampled low, the baud rate generator is loaded with the contents of SSPADD<6:0> and begins counting. The SDA pin is released (brought high) for one baud rate generator count (TBRG). When the baud rate generator times out, if SDA is sampled high, the SCL pin will be de-asserted (brought high). When SCL is sampled high the baud rate generator is reloaded with the contents of SSPADD<6:0> and begins counting. SDA and SCL must be sampled high for one TBRG. This action is then followed by assertion of the SDA pin (SDA is low) for one TBRG, while SCL is high. Following this, the RSEN bit in the SSPCON2 register will be automatically cleared and the baud rate generator will not be reloaded, leaving the SDA pin held low. As soon as a START condition is detected on the SDA and SCL pins, the S bit (SSPSTAT<3>) will be set. The SSPIF bit will not be set until the baud rate generator has timed out.

Note 1: If RSEN is programmed while any other event is in progress, it will not take effect.

2: A bus collision during the Repeated START condition occurs if:
- SDA is sampled low when SCL goes from low to high.
- SCL goes low before SDA is asserted low. This may indicate that another master is attempting to transmit a data "1".

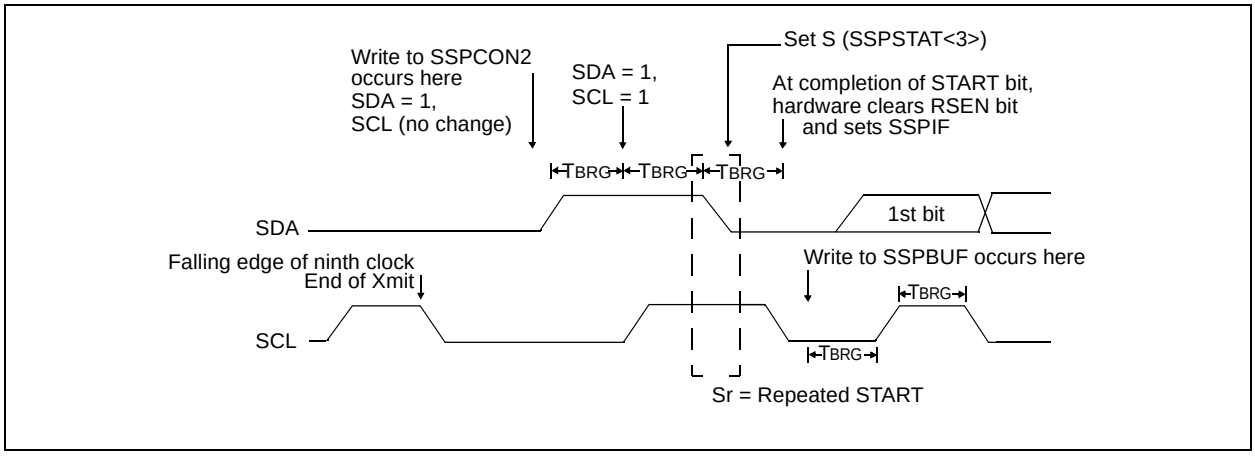
Immediately following the SSPIF bit getting set, the user may write the SSPBUF with the 7-bit address in 7-bit mode, or the default first address in 10-bit mode. After the first eight bits are transmitted and an ACK is received, the user may then transmit an additional eight bits of address (10-bit mode), or eight bits of data (7-bit mode).

9.2.10.1 WCOL Status Flag

If the user writes the SSPBUF when a Repeated START sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

Note: Because queueing of events is not allowed, writing of the lower 5 bits of SSPCON2 is disabled until the Repeated START condition is complete.

FIGURE 9-13: REPEAT START CONDITION WAVEFORM



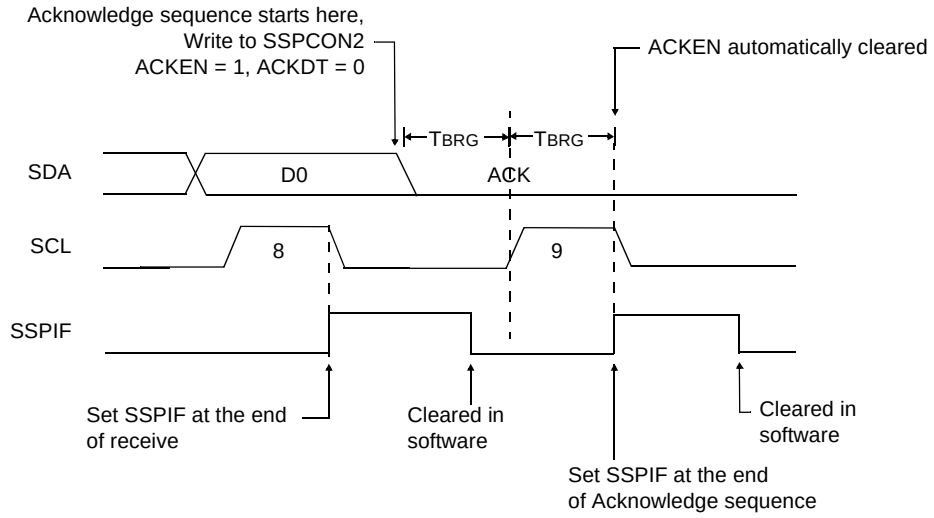
9.2.13 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge Sequence Enable bit, ACKEN (SSPCON2<4>). When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit is presented on the SDA pin. If the user wishes to generate an Acknowledge, the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The baud rate generator then counts for one rollover period (TBRG), and the SCL pin is de-asserted high. When the SCL pin is sampled high (clock arbitration), the baud rate generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the baud rate generator is turned off, and the SSP module then goes into IDLE mode (Figure 9-16).

9.2.13.1 WCOL Status Flag

If the user writes the SSPBUF when an Acknowledge sequence is in progress, the WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

FIGURE 9-16: ACKNOWLEDGE SEQUENCE WAVEFORM



Note: TBRG = one baud rate generator period.

TABLE 12-6: INITIALIZATION CONDITIONS FOR ALL REGISTERS

Register	Devices				Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets, WDT Reset	Wake-up via WDT or Interrupt
W	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	873	874	876	877	N/A	N/A	N/A
TMR0	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	873	874	876	877	0000h	0000h	PC + 1(2)
STATUS	873	874	876	877	0001 1xxx	000q quuu(3)	uuuq quuu(3)
FSR	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	873	874	876	877	--0x 0000	--0u 0000	--uu uuuu
PORTB	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTD	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTE	873	874	876	877	---- -xxx	---- -uuu	---- -uuu
PCLATH	873	874	876	877	---0 0000	---0 0000	---u uuuu
INTCON	873	874	876	877	0000 000x	0000 000u	uuuu uuuu(1)
PIR1	873	874	876	877	r000 0000	r000 0000	ruuu uuuu(1)
	873	874	876	877	0000 0000	0000 0000	uuuu uuuu(1)
PIR2	873	874	876	877	-r-0 0--0	-r-0 0--0	-r-u u--u(1)
TMR1L	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1H	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	873	874	876	877	--00 0000	--uu uuuu	--uu uuuu
TMR2	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
T2CON	873	874	876	877	-000 0000	-000 0000	-uuu uuuu
SSPBUF	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
SSPCON	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
CCPR1L	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1H	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	873	874	876	877	--00 0000	--00 0000	--uu uuuu
RCSTA	873	874	876	877	0000 000x	0000 000x	uuuu uuuu
TXREG	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
RCREG	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
CCPR2L	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR2H	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP2CON	873	874	876	877	0000 0000	0000 0000	uuuu uuuu
ADRESH	873	874	876	877	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	873	874	876	877	0000 00-0	0000 00-0	uuuu uu-u
OPTION_REG	873	874	876	877	1111 1111	1111 1111	uuuu uuuu
TRISA	873	874	876	877	--11 1111	--11 1111	--uu uuuu
TRISB	873	874	876	877	1111 1111	1111 1111	uuuu uuuu
TRISC	873	874	876	877	1111 1111	1111 1111	uuuu uuuu
TRISD	873	874	876	877	1111 1111	1111 1111	uuuu uuuu
TRISE	873	874	876	877	0000 -111	0000 -111	uuuu -uuu
PIE1	873	874	876	877	r000 0000	r000 0000	ruuu uuuu
	873	874	876	877	0000 0000	0000 0000	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition, r = reserved, maintain clear

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 12-5 for RESET value for specific condition.

14.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD for PIC16F87X
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

14.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

14.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PIC® MCUs.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

14.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

15.2 DC Characteristics: PIC16F873/874/876/877-04 (Commercial, Industrial) PIC16F873/874/876/877-20 (Commercial, Industrial) PIC16LF873/874/876/877-04 (Commercial, Industrial) (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC specification (Section 15.1)				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083		OSC2/CLKOUT (RC osc config)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	VOH	**Output High Voltage**					
D090		I/O ports(3)	VDD - 0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092		OSC2/CLKOUT (RC osc config)	VDD - 0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D150*	VOD	**Open-Drain High Voltage**	—	—	8.5	V	RA4 pin
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101	CIO	All I/O pins and OSC2 (RC mode)	—	—	50	pF	
D102	CB	SCL, SDA (I^2C mode)	—	—	400	pF	
		Data EEPROM Memory					
D120	ED	Endurance	100K	—	—	E/W	25°C at 5V
D121	VDRW	VDD for read/write	VMIN	—	5.5	V	Using EECON to read/write VMIN = min. operating voltage
D122	TDEW	Erase/write cycle time	—	4	8	ms	
		Program FLASH Memory					
D130	EP	Endurance	1000	—	—	E/W	25°C at 5V
D131	VPR	VDD for read	VMIN	—	5.5	V	VMIN = min operating voltage
D132A		VDD for erase/write	VMIN	—	5.5	V	Using EECON to read/write, VMIN = min. operating voltage
D133	TPEW	Erase/Write cycle time	—	4	8	ms	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16F87X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 15-13: SPI MASTER MODE TIMING (CKE = 0, SMP = 0)

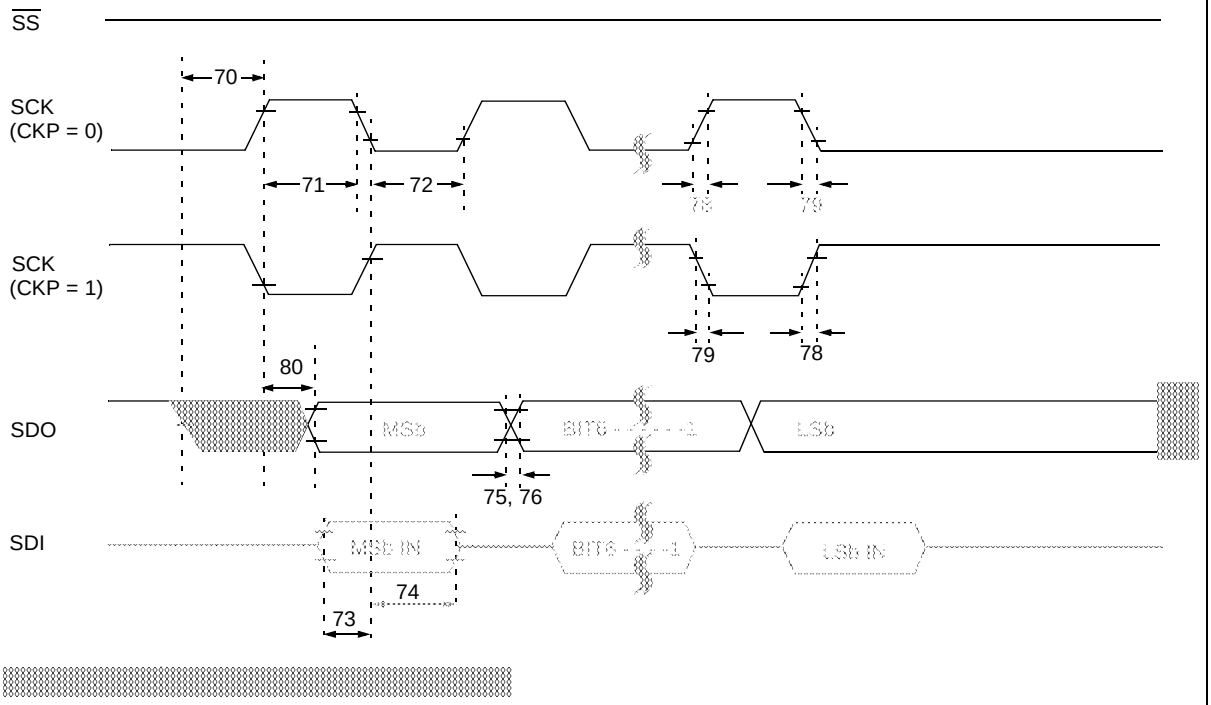
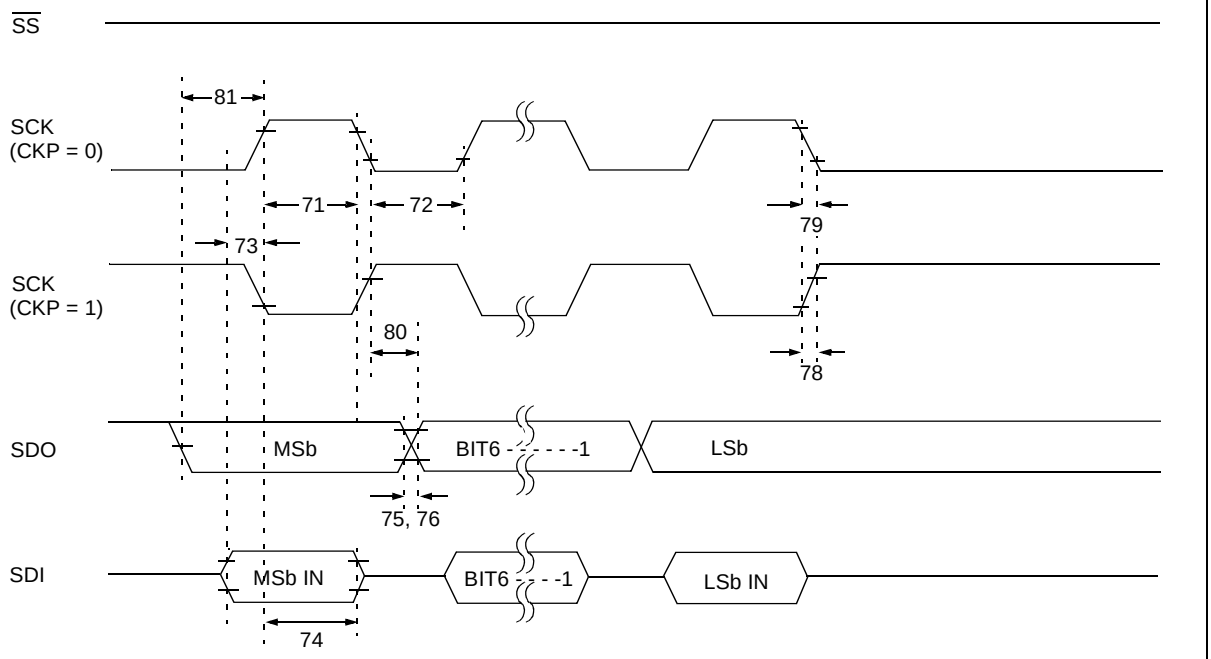
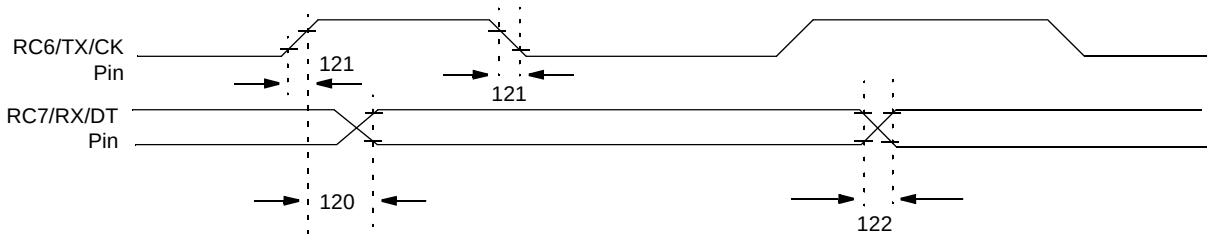


FIGURE 15-14: SPI MASTER MODE TIMING (CKE = 1, SMP = 1)



Note: Refer to Figure 15-5 for load conditions.

FIGURE 15-19: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



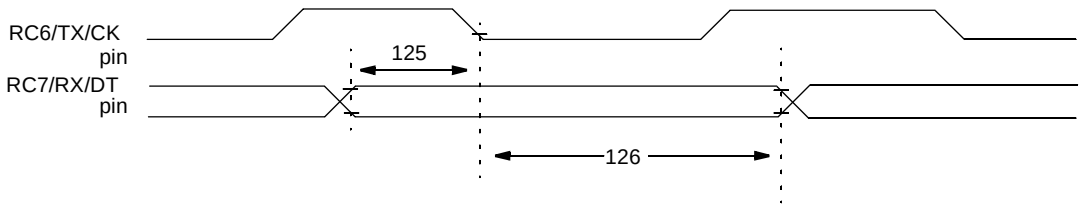
Note: Refer to Figure 15-5 for load conditions.

TABLE 15-10: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	Standard(**F**)	—	—	80	ns	
			Extended(**LF**)	—	—	100	ns	
121	Tckrf	Clock out rise time and fall time (Master mode)	Standard(**F**)	—	—	45	ns	
			Extended(**LF**)	—	—	50	ns	
122	Tdtrf	Data out rise time and fall time	Standard(**F**)	—	—	45	ns	
			Extended(**LF**)	—	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-20: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 15-5 for load conditions.

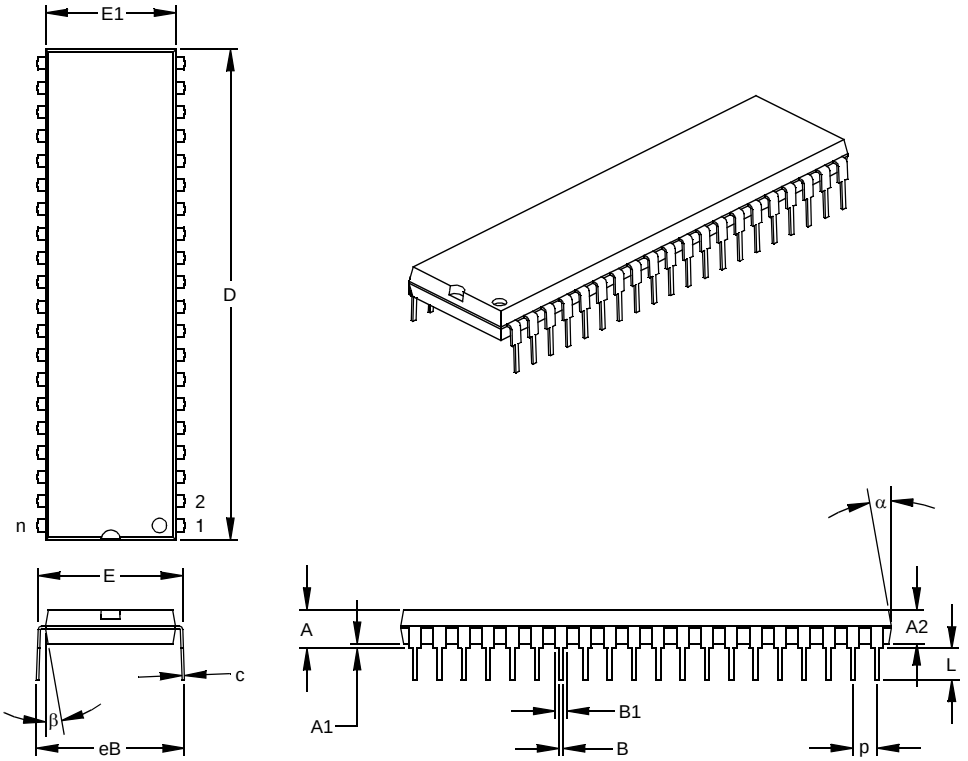
TABLE 15-11: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

40-Lead Plastic Dual In-line (P) – 600 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



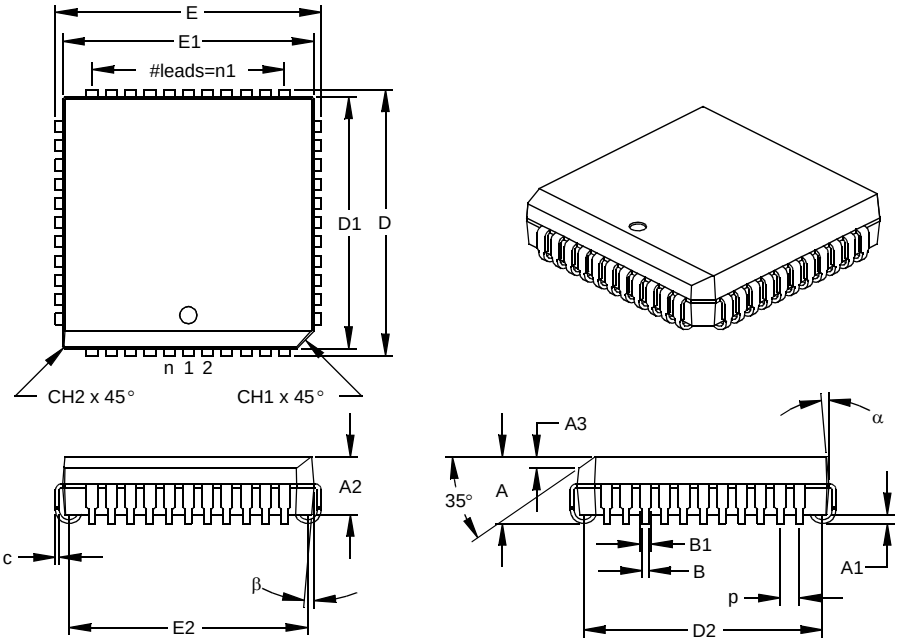
Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		40			40	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.160	.175	.190	4.06	4.45	4.83
Molded Package Thickness	A2	.140	.150	.160	3.56	3.81	4.06
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Molded Package Width	E1	.530	.545	.560	13.46	13.84	14.22
Overall Length	D	2.045	2.058	2.065	51.94	52.26	52.45
Tip to Seating Plane	L	.120	.130	.135	3.05	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.030	.050	.070	0.76	1.27	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.620	.650	.680	15.75	16.51	17.27
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-011
Drawing No. C04-016

44-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.050			1.27	
Pins per Side	n1		11			11	
Overall Height	A	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	E	.685	.690	.695	17.40	17.53	17.65
Overall Length	D	.685	.690	.695	17.40	17.53	17.65
Molded Package Width	E1	.650	.653	.656	16.51	16.59	16.66
Molded Package Length	D1	.650	.653	.656	16.51	16.59	16.66
Footprint Width	E2	.590	.620	.630	14.99	15.75	16.00
Footprint Length	D2	.590	.620	.630	14.99	15.75	16.00
Lead Thickness	c	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	B	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-047
Drawing No. C04-048